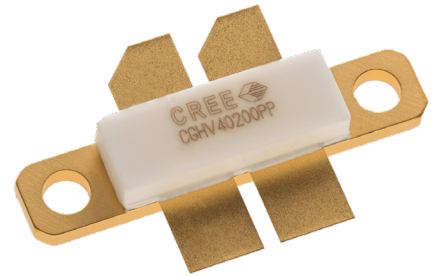


# CGHV40200PP

200 W, 50 V, GaN HEMT

## Description

Cree's CGHV40200PP is an unmatched, gallium nitride (GaN) high electron mobility transistor (HEMT). The CGHV40200PP, operating from a 50 volt rail, offers a general purpose, broadband solution to a variety of RF and microwave applications. GaN HEMTs offer high efficiency, high gain and wide bandwidth capabilities making the CGHV40200PP ideal for linear and compressed amplifier circuits. The transistor is available in a 4-lead flange package.



Package Type: 440199  
PN: CGHV40200PP

## Typical Performance Over 1.7-1.9 GHz ( $T_c = 25^\circ\text{C}$ ), CW

Parameter	1.7 GHz	1.8 GHz	1.9 GHz	Units
Small Signal Gain	21.7	21.0	20.1	dB
Gain @ $P_{IN} = 38\text{ dBm}$	16.5	16.1	15.4	dB
$P_{OUT}$ @ $P_{IN} = 38\text{ dBm}$	270	250	218	W
Drain Efficiency @ $P_{IN} = 38\text{ dBm}$	64	67	65	%

### Features

- Up to 3.0 GHz Operation
- 21 dB Small Signal Gain at 1.8 GHz
- 250 W typical  $P_{SAT}$
- 67% Efficiency at  $P_{SAT}$
- 50 V Operation

### Applications

- 2-Way Private Radio
- Broadband Amplifiers
- Cellular Infrastructure
- Test Instrumentation
- Class A, AB, Linear amplifiers suitable for OFDM, W-CDMA, EDGE, CDMA waveforms

 Large Signal Models Available for ADS and MWO

**RoHS**  
COMPLIANT

**Absolute Maximum Ratings (not simultaneous) at 25 °C Case Temperature**

Parameter	Symbol	Rating	Units	Conditions
Drain-Source Voltage	$V_{DSS}$	150	Volts	25 °C
Gate-to-Source Voltage	$V_{GS}$	-10, +2	Volts	25 °C
Storage Temperature	$T_{STG}$	-65, +150	°C	
Operating Junction Temperature	$T_J$	225	°C	
Maximum Forward Gate Current <sup>1</sup>	$I_{GMAX}$	41.6	mA	25 °C
Maximum Drain Current <sup>1</sup>	$I_{DMAX}$	8.7	A	25 °C
Soldering Temperature <sup>2</sup>	$T_S$	245	°C	
Screw Torque	$\tau$	40	in-oz	
Thermal Resistance, Junction to Case <sup>3</sup>	$R_{\theta JC}$	0.94	°C/W	85 °C
Case Operating Temperature <sup>3,4</sup>	$T_C$	-40, +70	°C	

Notes:

<sup>1</sup> Current limit for long term, reliable operation per side of the device<sup>2</sup> Refer to the Application Note on soldering at [wolfspeed.com/rf/document-library](http://wolfspeed.com/rf/document-library)<sup>3</sup> CGHV40200PP at  $P_{DISS} = 166$  W<sup>4</sup> See also, the Power Dissipation De-rating Curve on Page**Electrical Characteristics ( $T_C = 25$  °C)**

Characteristics	Symbol	Min.	Typ.	Max.	Units	Conditions
<b>DC Characteristics<sup>1</sup></b>						
Gate Threshold Voltage	$V_{GS(th)}$	-3.8	-3.0	-2.3	$V_{DC}$	$V_{DS} = 10$ V, $I_D = 41.6$ mA
Gate Quiescent Voltage	$V_{GS(Q)}$	-	-2.7	-	$V_{DC}$	$V_{DS} = 50$ V, $I_D = 2.0$ A
Saturated Drain Current <sup>2</sup>	$I_{DS}$	27.0	38.7	-	A	$V_{DS} = 6.0$ V, $V_{GS} = 2.0$ V
Drain-Source Breakdown Voltage	$V_{BR}$	125	-	-	$V_{DC}$	$V_{GS} = -8$ V, $I_D = 41.6$ mA
<b>RF Characteristics<sup>3,4</sup> (<math>T_C = 25</math> °C, <math>F_0 = 1.8</math> GHz unless otherwise noted)</b>						
Small Signal Gain	$G_{SS}$	17.75	20.0	-	dB	$V_{DD} = 50$ V, $I_{DQ} = 1.2$ A, $P_{IN} = 10$ dBm
Power Gain	$P_G$	15.05	16.0	-	dB	$V_{DD} = 50$ V, $I_{DQ} = 1.2$ A, $P_{IN} = 38$ dBm
Power Output	$P_{OUT}$	200	250	-	W	$V_{DD} = 50$ V, $I_{DQ} = 1.2$ A, $P_{IN} = 38$ dBm
Drain Efficiency <sup>5</sup>	$\eta$	60	69	-	%	$V_{DD} = 50$ V, $I_{DQ} = 1.2$ A, $P_{IN} = 38$ dBm
Output Mismatch Stress	VSWR	-	-	3 : 1	$\Psi$	No damage at all phase angles, $V_{DD} = 50$ V, $I_{DQ} = 1.2$ A, $P_{OUT} = 200$ W CW
<b>Dynamic Characteristics<sup>6</sup></b>						
Input Capacitance	$C_{GS}$	-	29.3	-	pF	$V_{DS} = 28$ V, $V_{GS} = -8$ V, $f = 1$ MHz
Output Capacitance	$C_{DS}$	-	7.3	-	pF	$V_{DS} = 28$ V, $V_{GS} = -8$ V, $f = 1$ MHz
Feedback Capacitance	$C_{GD}$	-	0.61	-	pF	$V_{DS} = 28$ V, $V_{GS} = -8$ V, $f = 1$ MHz

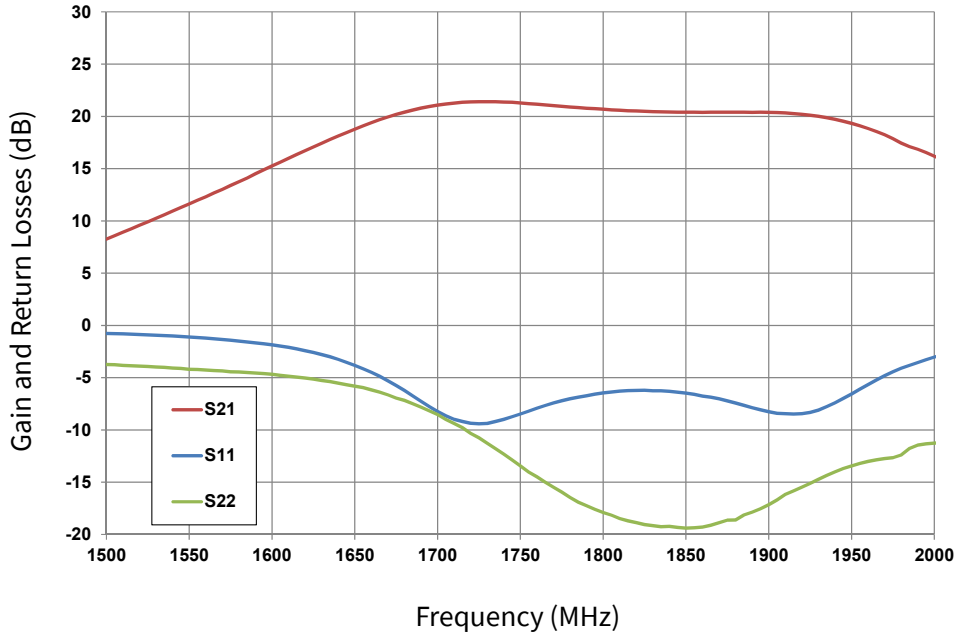
Notes:

<sup>1</sup> Measured on wafer prior to packaging per side of device<sup>2</sup> Scaled from PCM data<sup>3</sup> Measured in CGHV40200PP-TB<sup>4</sup>  $I_{DQ}$  of 1.2 A is by biasing each device at 0.6 A<sup>5</sup> Drain Efficiency =  $P_{OUT} / P_{DC}$ <sup>6</sup> Capacitance values are for each side of the device

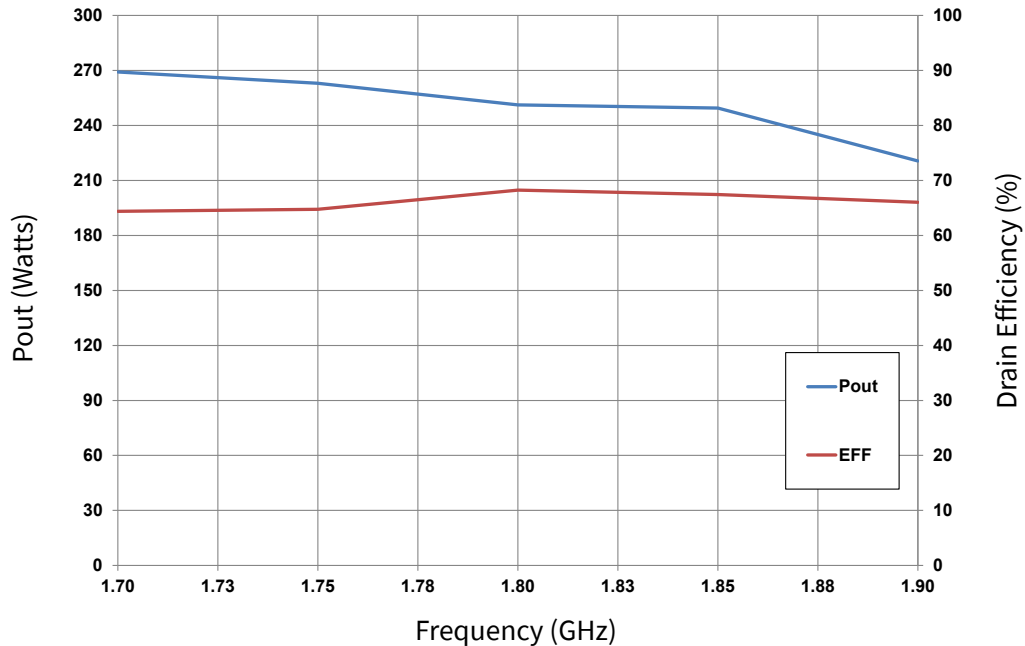


Typical Performance

**Figure 1. Gain and Return Losses vs Frequency measured in CGHV40200PP-TB**  
 $V_{DD} = 50\text{ V}$ ,  $I_{DQ} = 1.2\text{ A}$ , Freq = 1500 - 2000 MHz



**Figure 2. Output Power and Drain Efficiency vs Frequency measured in CGHV40200PP-TB**  
 CW Operation,  $V_{DD} = 50\text{ V}$ ,  $I_{DQ} = 1.2\text{ A}$ , Output Power @  $P_{IN} = 38\text{ dBm}$





Typical Performance

Figure 3. Gain and Drain Efficiency vs Output Power measured in CGHV40200PP-TB  
 CW Operation,  $V_{DD} = 50\text{ V}$ ,  $I_{DQ} = 1.2\text{ A}$

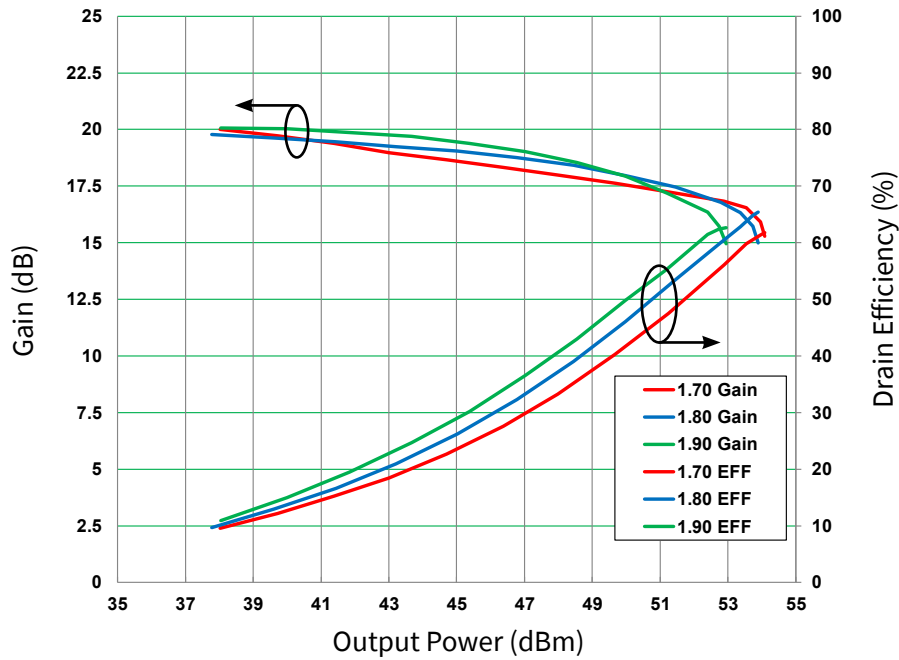
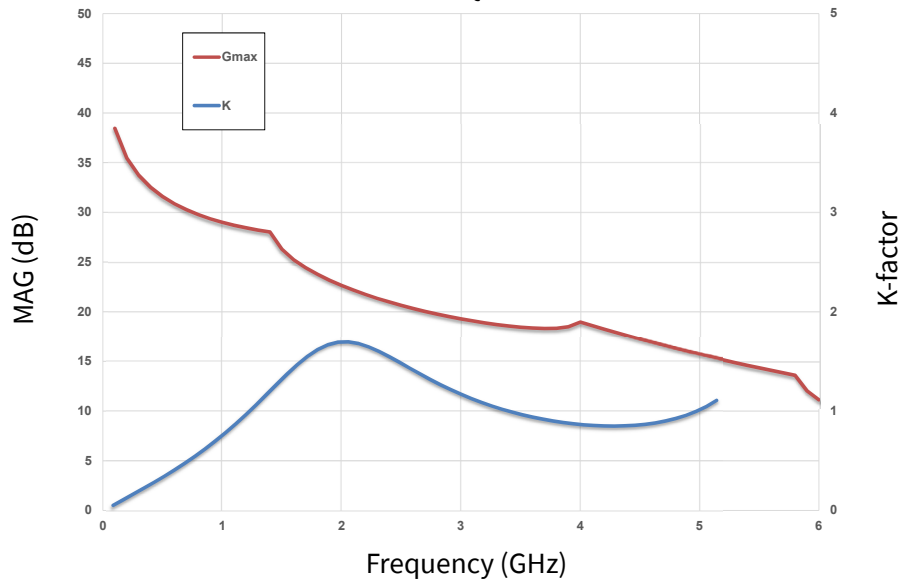


Figure 4. Simulated Maximum Available Gain and K-factor of the CGHV40200PP  
 $V_{DD} = 50\text{ V}$ ,  $I_{DQ} = 1.2\text{ A}$



Electrostatic Discharge (ESD) Classifications

Parameter	Symbol	Class	Test Methodology
Human Body Model	HBM	1A > 250 V	JEDEC JESD22 A114-D
Charge Device Model	CDM	1 < 200 V	JEDEC JESD22 C101-C

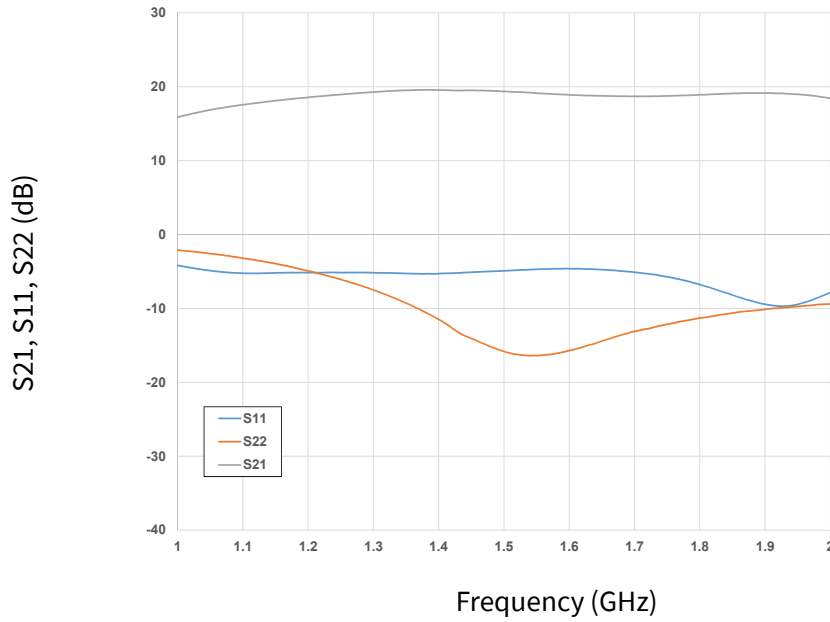
**CGHV40200PP-AMP1 Demonstration Amplifier Circuit Bill of Materials**

Designator	Description	Qty
R1,2	RES,1/4W,1206 1%, 0 OHM	2
R5, R6, R7,R11, R12, R13	RES, 1/16W, 0603, 1%, 5.1 Ohms	6
R3, R4, R9, R10	RES 5.1 OHM 1/8W 5% 0805 SMD	4
R15, R16, R17, R18	RES SMD 10 OHM 1% 2W 2512	4
R8,14	RES SMD 150 OHM 5% 1W 2512	2
C48,49	CAP, 0.1PF, +/- 0.05pF, 0805, ATC, 600F	2
C16	CAP, 0.8pF, +/-0.05pF, 0805, ATC	1
C27	CAP, 1.2pF, +/-0.1pF, 0603, ATC	1
C24	CAP, 1.2pF, +/-0.1pF, 0805, ATC	1
C15	CAP, 1.0pF, +/-0.1pF, 0603, ATC	1
C26	CAP, 1.5pF,+/-0.1pF, 0603, ATC	1
C25	CAP, 2.0pF, +/-0.1pF, 0805, ATC	1
C17	CAP, 3.9pF,+/-0.25pF, 0805, ATC	1
C28,29,36,37, 42, 46	CAP, 5.1pF, +/-0.05pF, 0805, ATC600F	4
C5,6,38,39	CAP, 5.6 PF +/- 0.1 pF, 0805, ATC 600F	4
C4,7,31,35	CAP, 20PF ±5% 250V 0805, ATC600F	4
C32,33,44,47	CAP, 100 PF +/- 5%, 250V, 0805, ATC 600F	4
C2,3,8,9,13,18,30, 34,40,41, 43, 45	CAP, 1000PF, +/-10%, 0805, X7R, 100V, TEMP STBL	12
C1,11,14,19,22,23,	CAP, 10000PF, +/-10%, 0805, X7R, 100V, TEMP STBL	6
C21	CAP, 0.1uF, +/-10%, 250V, 1206, X7R	1
C10,12	CAP CER 10UF 25V X7R 1206	2
C20	CAP, 330 UF, +/-20%, 100V, ELECTROLYTIC, CASE SIZE K16	1
L6,7, 9,10,12, 13	IND, 12NH, 2%, 0908SQ-12NGL	6
L2, 3	IND, 27NH, 2%, 0908SQ-27NGL	2
L11	CABLE ,18 AWG, 4.2"	1
L1,4	FERRITE BEAD 600 OHM 0603 1LN	2
L5,8	FERRITE BEAD 72 OHM 1806 1LN	2
J2,3	CONN, SMA, PANEL MOUNT JACK, FLANGE, 4-HOLE, BLUNT POST	2
J1	HEADER RT>PLZ .1CEN LK 9POS	1
J4,5	CONN SMA JACK STR 50 OHM SMD	2
	PCB, Rogers 6035HTC 0.020" THK, CGHV40200PP 1.35-1.85 GHz	1
	BASEPLATE, AL, 4.80 X 3.60 X 0.49, ALTERNATE HOLE PATTERN	1
	2-56 SOC HD SCREW 1/4 SS	4
	#2 SPLIT LOCKWASHER SS	4
	CGHV40200PPP	1

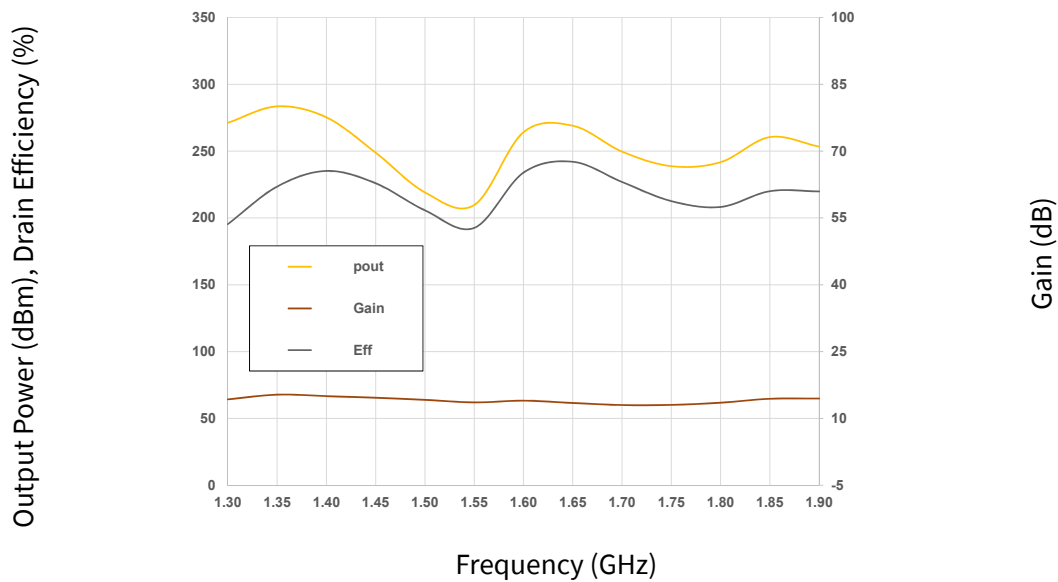


**CGHV40200F Typical Performance**

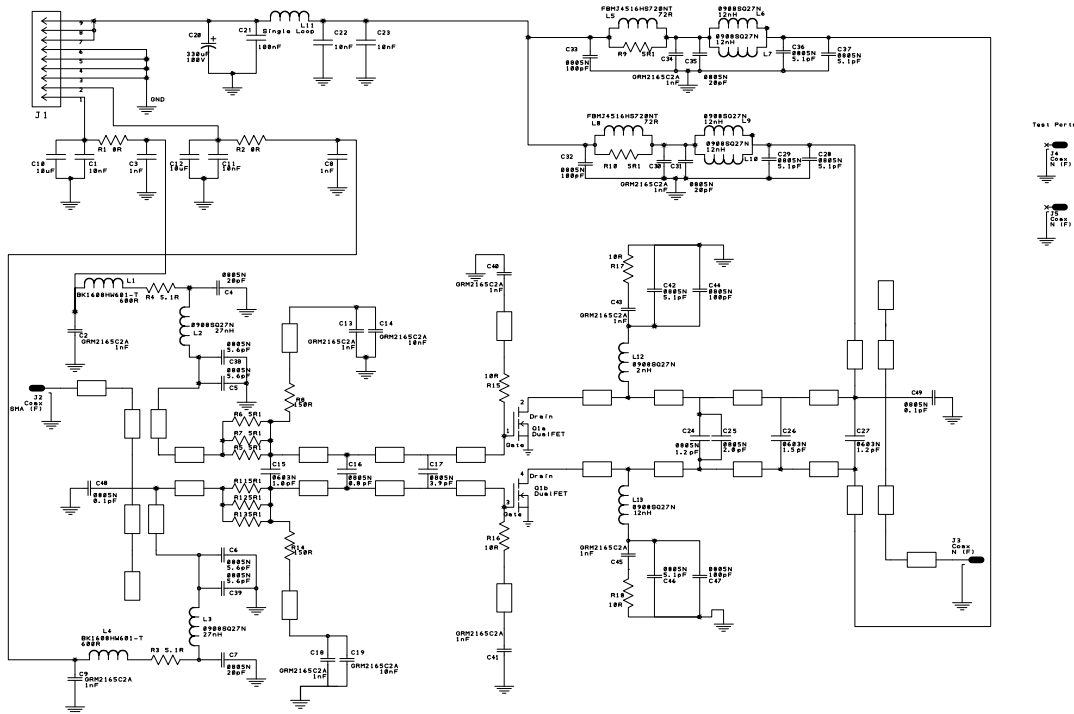
**Figure 5. Small Signal Gain and Return Losses vs Frequency measured in the CGHV40200PP-AMP1 Broadband Amplifier Circuit**  
 $V_{DD} = 50\text{ V}, I_{DQ} = 1.2\text{ A}$



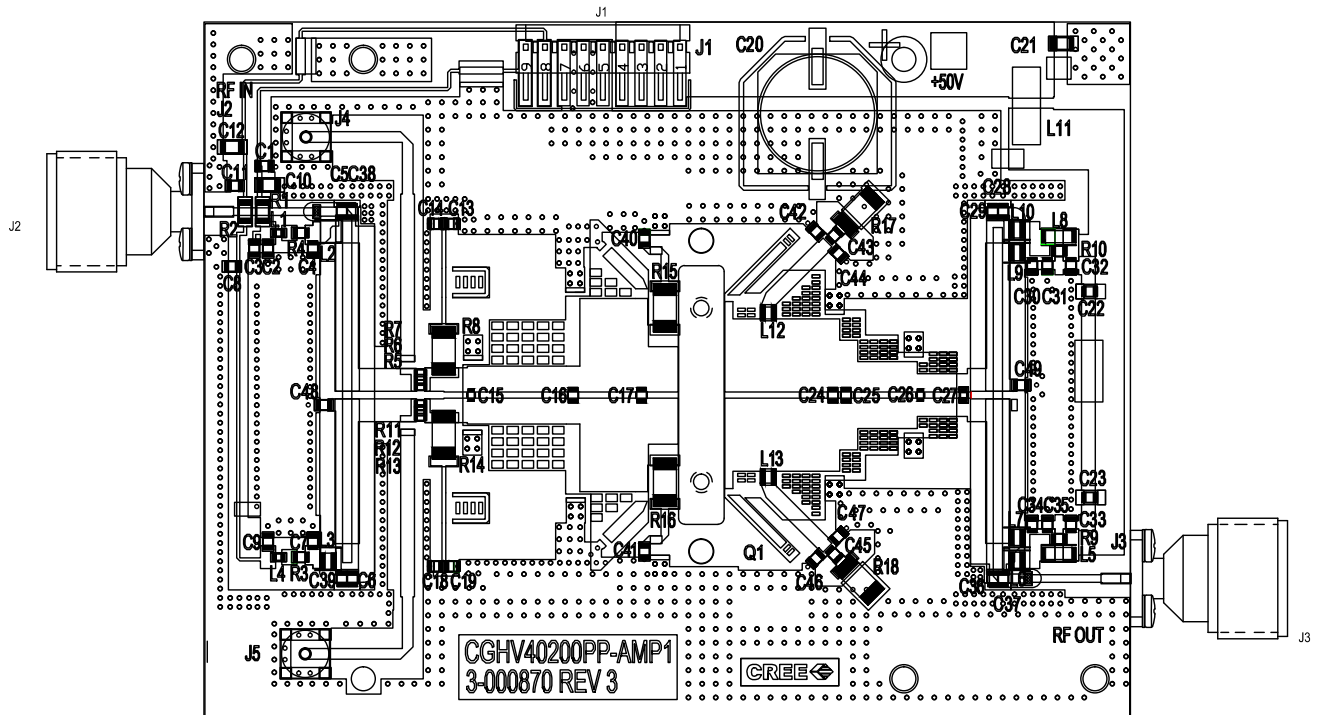
**Figure 6. Saturated Output Power Gain, and Drain Efficiency vs Frequency of the CGHV40200PP measured in the CGHV40200PP-AMP1 Broadband Amplifier Circuit**  
 $V_{DD} = 50\text{ V}, I_{DQ} = 1\text{ A}, \text{CW}, P_{SAT}, I_G = 0\text{ mA}$



### CGHV40200PP-AMP1 Demonstration Amplifier Circuit Schematic

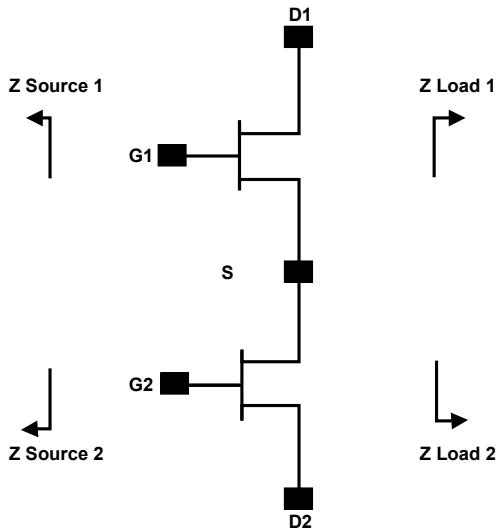


### CGHV40200PP-AMP1 Demonstration Amplifier Circuit Outline





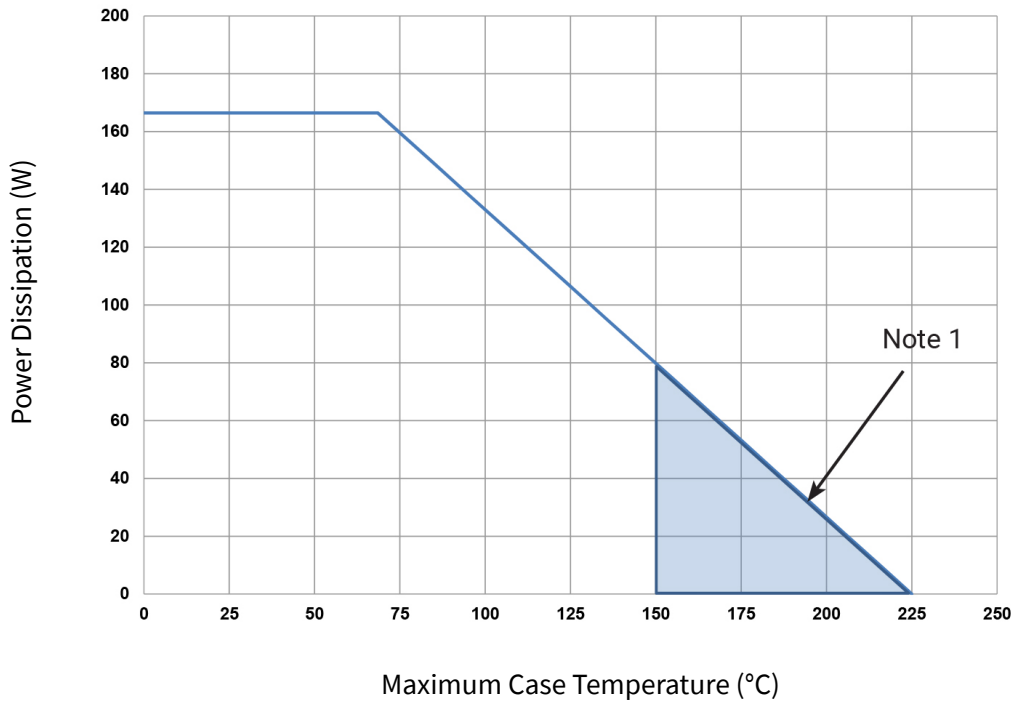
### Simulated Source and Load Impedances



Frequency (MHz)	Z Source (1,2)	Z Load (1,2)
500	2.9 +j4.8	12.8 +j7.3
1000	0.8 +j1.5	9.1 +j5.1
1500	0.9 +j0.6	5.5 +j3.8
2000	1.1 -j2.2	4.4 +j2.0
2500	1.8 -j4.0	3.8 +j0.5

Note 1.  $V_{DD} = 50\text{ V}$ ,  $I_{DQ} = 2 \times 0.6\text{ A}$  in the 440199 package  
 Note 2. Optimized for power gain,  $P_{SAT}$  and PAE  
 Note 3. When using this device at low frequency, series resistors should be used to maintain amplifier stability

### CGHV40200PP Power Dissipation De-rating Curve

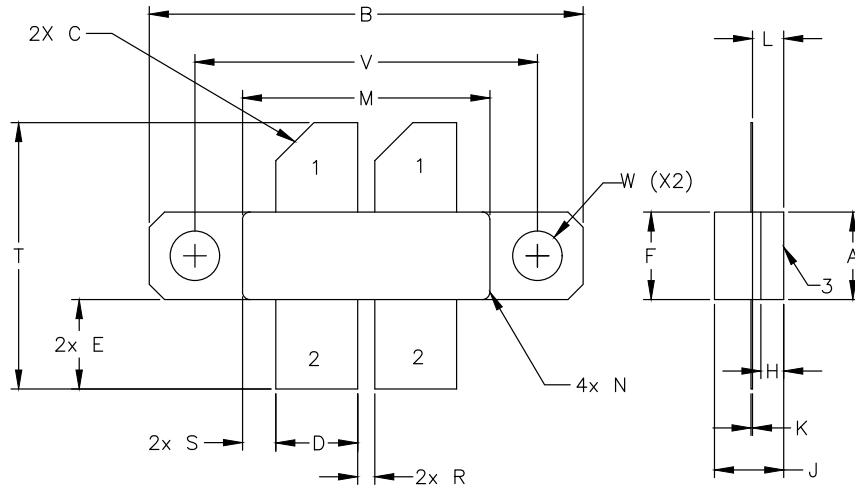


Note 1. Area exceeds Maximum Case Operating Temperature (See Page 2)





**Product Dimensions CGHV40200PP (Package Type 440199)**



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.225	0.235	5.72	5.97
B	1.135	1.145	28.83	29.00
C	0.10	45° REF	2.54	45° REF
D	0.210	0.220	5.33	5.59
E	0.230	0.240	5.84	6.00
F	0.225	0.235	5.71	5.97
H	0.055	0.065	1.40	1.65
J	0.174	0.208	3.87	4.37
K	0.003	0.006	0.08	0.15
L	0.075	0.085	1.91	2.16
M	0.643	0.657	16.30	16.70
N	R.010 REF		R0.51 REF	
R	0.040	0.050	1.00	1.27
S	0.083	0.093	2.10	2.36
T	0.680	0.720	17.30	18.30
V	0.895	0.905	22.70	22.98
W	ø.130		ø 3.30	

**Part Number System**

**CGHV40200PP**



**Table 1.**

Parameter	Value	Units
Upper Frequency <sup>1</sup>	2.5	GHz
Power Output	200	W
Package	Push Pill	-

**Note<sup>1</sup>:** Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value

**Table 2.**

Character Code	Code Value
A	0
B	1
C	2
D	3
E	4
F	5
G	6
H	7
J	8
K	9
Examples:	1A = 10.0 GHz 2H = 27.0 GHz



**Product Ordering Information**

Order Number	Description	Unit of Measure	Image
CGHV40200PP	GaN HEMT	Each	
CGHV40200PP-AMP1	Test board with GaN HEMT installed	Each	



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## Notes

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